





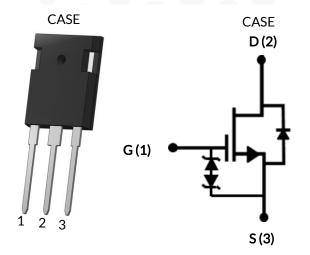








UJ3C120150K3S



Part Number	Part Number Package	
UJ3C120150K3S	TO-247-3L	UJ3C120150K3S









1200V-150m Ω SiC FET

Rev. C. December 2019

Description

This SiC FET device is based on a unique 'cascode' circuit configuration, in which a normally-on SiC JFET is co-packaged with a Si MOSFET to produce a normally-off SiC FET device. The device's standard gate-drive characteristics allows for a true "drop-in replacement" to Si IGBTs, Si FETs, SiC MOSFETs or Si superjunction devices. Available in the TO-247-3L package, this device exhibits ultralow gate charge and exceptional reverse recovery characteristics, making it ideal for switching inductive loads, and any application requiring standard gate drive.

Features

- Typical on-resistance $R_{DS(on),typ}$ of $150m\Omega$
- Maximum operating temperature of 175°C
- Excellent reverse recovery
- Low gate charge
- Low intrinsic capacitance
- ESD protected, HBM class 2

Typical applications

- EV charging
- PV inverters
- Switch mode power supplies
- Power factor correction modules
- Motor drives
- Induction heating













Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
Drain-source voltage	V_{DS}		1200	V
Gate-source voltage	V_{GS}	DC	-25 to +25	V
Continuous drain current ¹	I _D	T _C = 25°C	18.4	Α
Continuous drain current		T _C = 100°C	13.8	Α
Pulsed drain current ²	I _{DM}	T _C = 25°C	38	Α
Single pulsed avalanche energy ³	E _{AS}	L=15mH, I _{AS} =2A	30	mJ
Power dissipation	P _{tot}	T _C = 25°C	166.7	W
Maximum junction temperature	$T_{J,max}$		175	°C
Operating and storage temperature	T_J, T_{STG}		-55 to 175	°C
Max. lead temperature for soldering, 1/8" from case for 5 seconds	T _L		250	°C

- 1. Limited by $T_{J,\text{max}}$
- 2. Pulse width t_p limited by $T_{J,max}$
- 3. Starting $T_J = 25^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Test Conditions	Value			Units
			Min	Тур	Max	Offics
Thermal resistance, junction-to-case	$R_{ heta$ JC			0.7	0.9	°C/W













Electrical Characteristics (T_J = +25°C unless otherwise specified)

Typical Performance - Static

Parameter	Symbol	Test Conditions		Units		
			Min	Тур	Max	UIIILS
Drain-source breakdown voltage	BV _{DS}	V_{GS} =0V, I_D =1mA	1200			V
		V _{DS} =1200V,		2	50	- μΑ
Total drain leakage current	l	$V_{GS}=0V, T_J=25$ °C				
Total di alli leakage cui i elli	I _{DSS}	V _{DS} =1200V,		17		
		$V_{GS}=0V, T_J=175$ °C				
Total gate leakage current	I _{GSS}	V _{DS} =0V, T _J =25°C,		4	±20	μА
		V_{GS} =-20V / +20V				
	R _{DS(on)}	V _{GS} =12V, I _D =5A,		150	180	
		T _J =25°C				
Drain-source on-resistance		V_{GS} =12V, I_{D} =5A,		250		mΩ
		T _J =125°C				
		V_{GS} =12V, I_D =5A,		330		
		175°C ا _ر T				
Gate threshold voltage	$V_{G(th)}$	V_{DS} =5V, I_{D} =10mA	3.5	4.4	5.5	V
Gate resistance	R_{G}	f=1MHz, open drain		4.6		Ω

Typical Performance - Reverse Diode

Parameter	Symbol	Test Conditions		Units		
Parameter			Min	Тур	Max	Units
Diode continuous forward current ¹	I _S	T _C =25°C			18.4	Α
Diode pulse current ²	I _{S,pulse}	T _C =25°C			38	Α
Forward voltage	V _{FSD}	V _{GS} =0V, I _F =5A, T _J =25°C		1.46	2	. V
		V _{GS} =0V, I _F =5A, T _J =175°C		2		
Reverse recovery charge	Q _{rr}	V_R =800V, I_F =13A, V_{GS} =0V, R_{G_EXT} =20 Ω di/dt=1700A/ μ s, T_J =150°C		63		nC
Reverse recovery time	t _{rr}			28		ns













Typical Performance - Dynamic

Parameter	Symbol	Test Conditions	Value			Units
			Min	Тур	Max	Offics
Input capacitance	C _{iss}	\/ -100\/ \/ -0\/		738		
Output capacitance	C _{oss}	- V _{DS} =100V, V _{GS} =0V - f=100kHz		58		pF
Reverse transfer capacitance	C_{rss}	1-100KH2		1.8		
Effective output capacitance, energy related	C _{oss(er)}	V_{DS} =0V to 800V, V_{GS} =0V		34		pF
Effective output capacitance, time related	C _{oss(tr)}	V_{DS} =0V to 800V, V_{GS} =0V		68		pF
C _{OSS} stored energy	E _{oss}	V_{DS} =800V, V_{GS} =0V		10.8		μЈ
Total gate charge	Q_{G}	$V_{DS}=800V, I_{D}=13A, V_{GS}=-5V \text{ to } 15V$		30		
Gate-drain charge	Q_{GD}			6		nC
Gate-source charge	Q_{GS}			10		
Turn-on delay time	$t_{d(on)}$	$\begin{aligned} & V_{DS}\text{=}800\text{V, } I_{D}\text{=}13\text{A, Gate} \\ & \text{Driver =-5V to +15V,} \\ & \text{Turn-on } R_{G,EXT}\text{=}1\Omega, \\ & \text{Turn-off } R_{G,EXT}\text{=}20\Omega \\ & \text{Inductive Load,} \\ & \text{FWD: UJ3D1205TS} \\ & & T_{J}\text{=}150^{\circ}\text{C} \end{aligned}$		21		
Rise time	t _r			10		nc
Turn-off delay time	$t_{d(off)}$			36		ns
Fall time	t _f			7		
Turn-on energy	E _{ON}			175		
Turn-off energy	E _{OFF}			46		μЈ
Total switching energy	E _{TOTAL}			221		





40

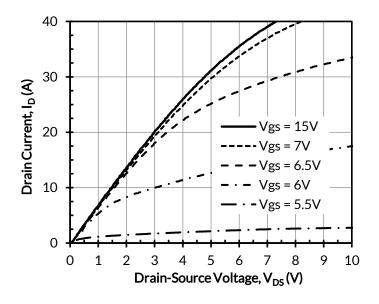








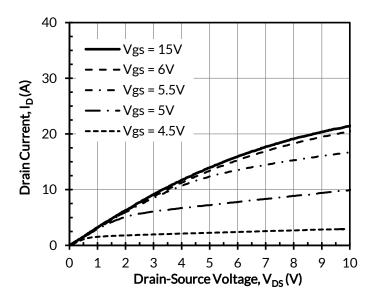
Typical Performance Diagrams



30 Drain Current, I_D (A) 20 Vgs = 15V Vgs = 7V Vgs = 6.5V10 Vgs = 6V Vgs = 5.5V0 0 1 2 10 5 Drain-Source Voltage, $V_{DS}(V)$

Figure 1. Typical output characteristics at $T_J = -55$ °C, tp < 250 μ s

Figure 2. Typical output characteristics at $T_J = 25$ °C, tp < 250 μ s



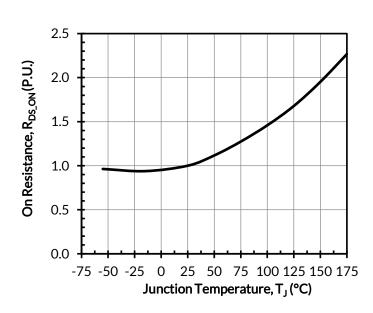


Figure 3. Typical output characteristics at T_J = 175°C, tp < 250 μ s

Figure 4. Normalized on-resistance vs. temperature at V_{GS} = 12V and I_{D} = 5A



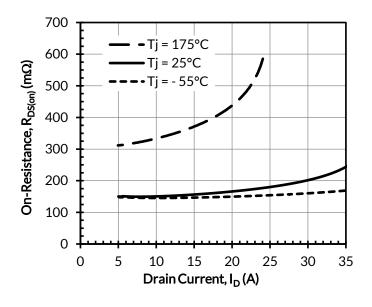








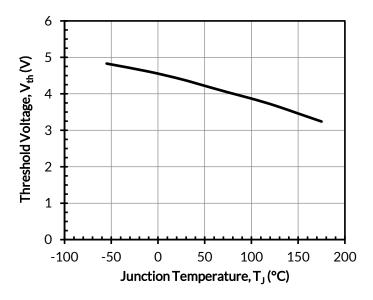




Tj = -55°C Tj = 25°C Drain Current, I_D (A) Tj = 175°C Gate-Source Voltage, $V_{GS}(V)$

Figure 5. Typical drain-source on-resistances at V_{GS} = 12V

Figure 6. Typical transfer characteristics at $V_{DS} = 5V$



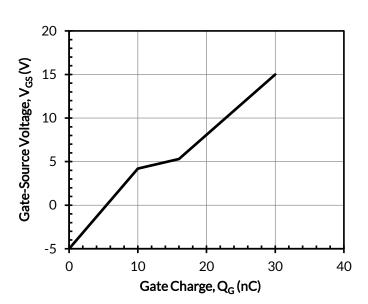


Figure 7. Threshold voltage vs. junction temperature at V_{DS} = 5V and I_{D} = 10mA

Figure 8. Typical gate charge at V_{DS} = 800V and I_{D} = 13A













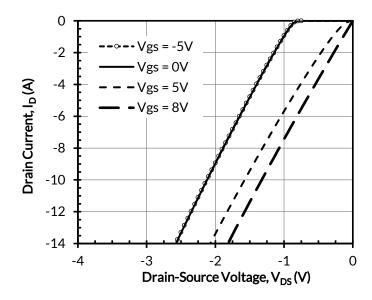


Figure 9. 3rd quadrant characteristics at T_J = -55°C

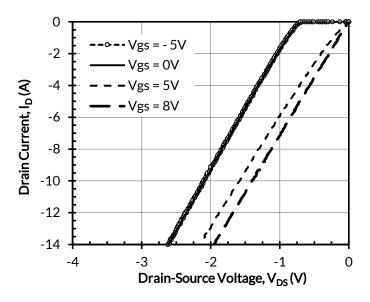


Figure 10. 3rd quadrant characteristics at T_J = 25°C

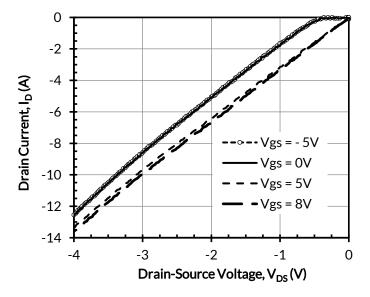


Figure 11. 3rd quadrant characteristics at $T_J = 175$ °C

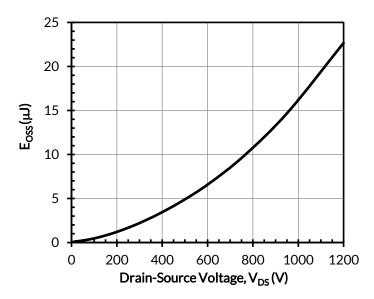


Figure 12. Typical stored energy in C_{OSS} at $V_{GS} = 0V$



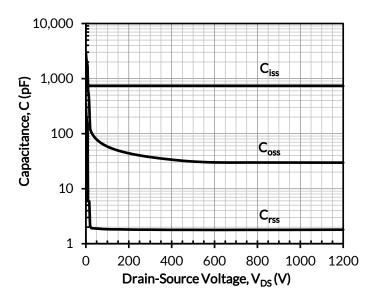








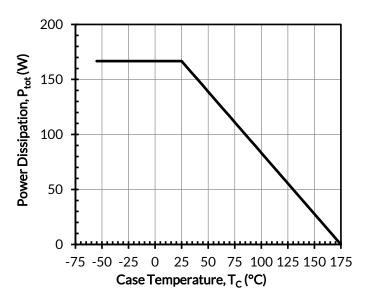




20 18 16 14 12 10 10 10 -75 -50 -25 0 25 50 75 100 125 150 175 Case Temperature, T_C (°C)

Figure 13. Typical capacitances at f = 100kHz and $V_{GS} = 0V$

Figure 14. DC drain current derating



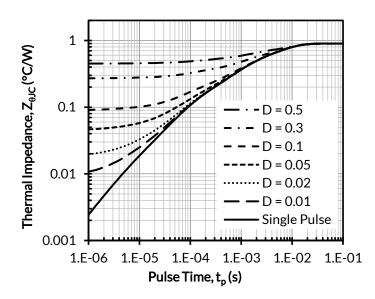


Figure 15. Total power dissipation

Figure 16. Maximum transient thermal impedance













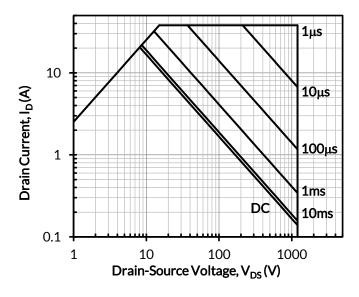


Figure 17. Safe operation area at T_C = 25°C, D = 0, Parameter t_p

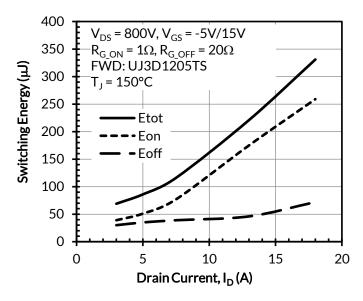


Figure 18. Clamped inductive switching energy vs. drain current at $T_J = 150$ °C

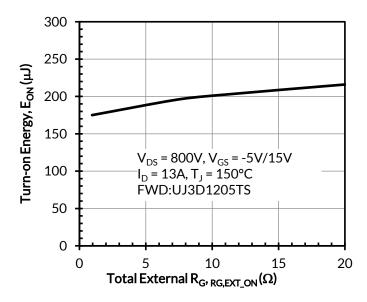


Figure 19. Clamped inductive switching turn-on energy vs. R_{G,EXT_ON}

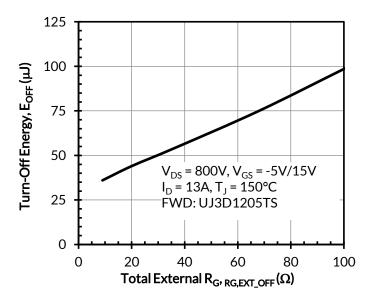


Figure 20. Clamped inductive switching turn-off energy vs. R_{G,EXT_OFF}













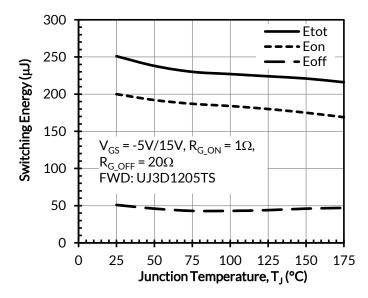


Figure 21. Clamped inductive switching energy vs. junction temperature at V_{DS} = 800V and I_D = 13A

Applications Information

SiC FETs are enhancement-mode power switches formed by a high-voltage SiC depletion-mode JFET and a low-voltage silicon MOSFET connected in series. The silicon MOSFET serves as the control unit while the SiC JFET provides high voltage blocking in the off state. This combination of devices in a single package provides compatibility with standard gate drivers and offers superior performance in terms of low on-resistance ($R_{\rm DS(on)}$), output capacitance ($C_{\rm oss}$), gate charge ($Q_{\rm G}$), and reverse recovery charge (Qrr) leading to low conduction and switching losses. The SiC FETs also provide excellent reverse conduction capability eliminating the need for an external anti-parallel diode.

Like other high performance power switches, proper PCB layout design to minimize circuit parasitics is strongly recommended due to the high dv/dt and di/dt rates. An external gate resistor is recommended when the FET is working in the diode mode in order to achieve the optimum reverse recovery performance. For more information on SiC FET operation, see www.unitedsic.com.

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